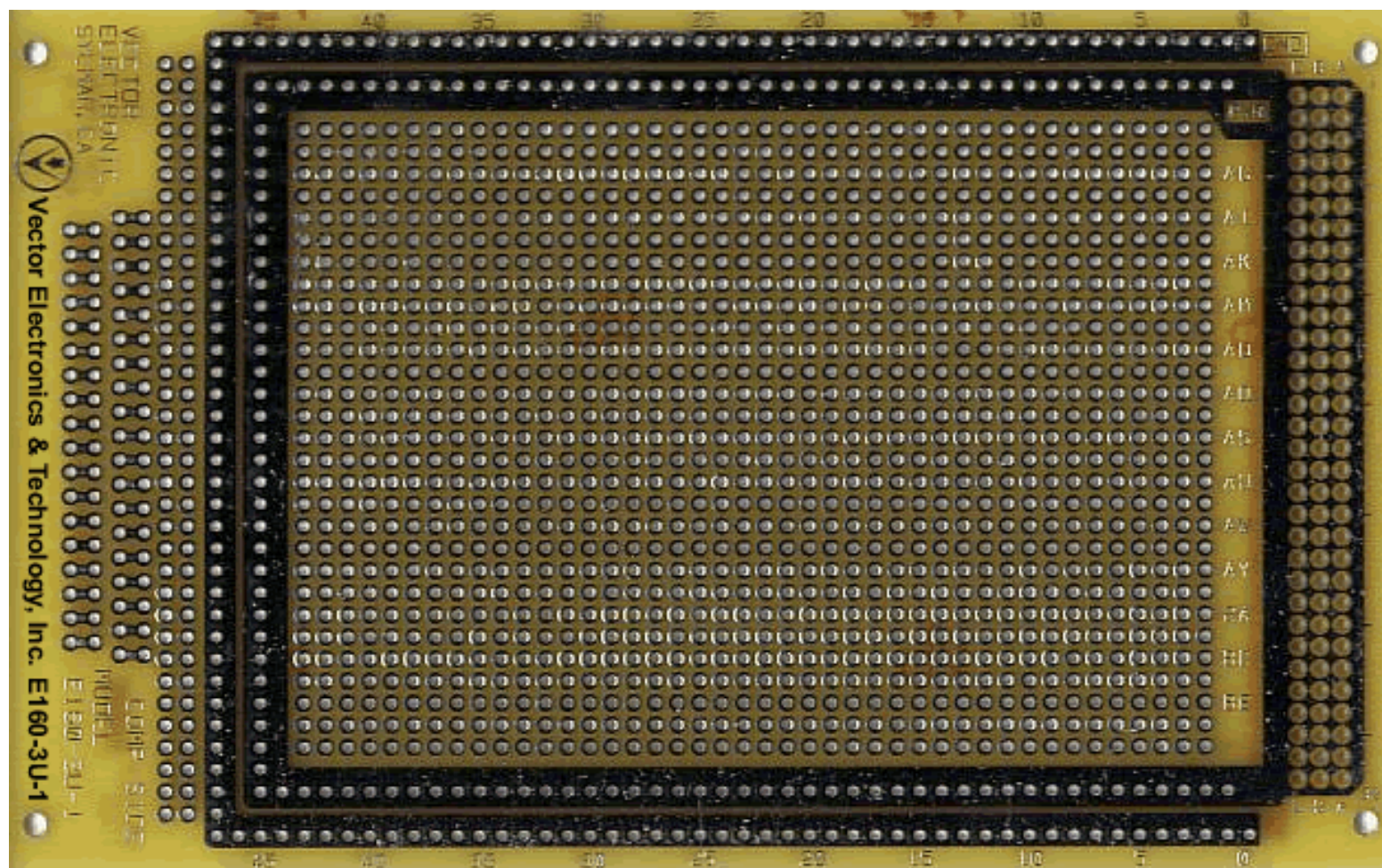


3U EUROCARD PLUGBORD™ PART NO. : E160-3U-1



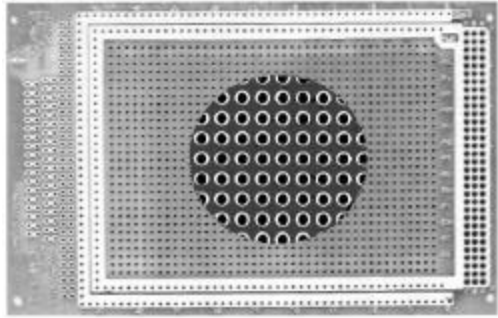
Description :

- 3U x 160 mm, Hole Dia.: 0.042", Grid: 0.100" x 0.100"
- Pad-Per-Hole
- Voltage and ground buses around board perimeter on both sides.
- Isolated solder pad around each hole on both sides
- Pad and bus surfaces solder-coated for user convenience
- For solder, Wire-Wrap or mixed wiring methods
- Plated-thru holes
- Layout paper and instructions included [Layout Paper\(PDF\)](#)
- Row and column legends provided

Circuit Pattern :	Pad-Per-Hole
16 Pin DIP Capacity :	35
Hole Diameter :	0.042" { 1.0668 mm }
Grid :	0.100" x 0.100" { 2.54mm X 2.54mm }
Dimension { H, W, T } :	3.94" x 6.30" x 0.062"
Material :	FR4 Epoxy Glass { MIL - P13949 type Gf }
Wire-Wrap Terminals :	T44, T46, T49, T68
96 Pin DIN Connector :	RE96MWR (available separately)
Wire-Wrap Socket Pins :	R32
Recommended Card Cage:	CCK 160-3U Series Card Cage { Subracks }
NEMA Grade :	FR4
UL Flammability Class :	94V - 0

Eurocard - for 96 Pin DIN

3U

**E160-3U-1**

Circuit Pattern:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Rec. Card Cage:
96-Pin Din Connector:

Hole Diameter:

3Ux160mm

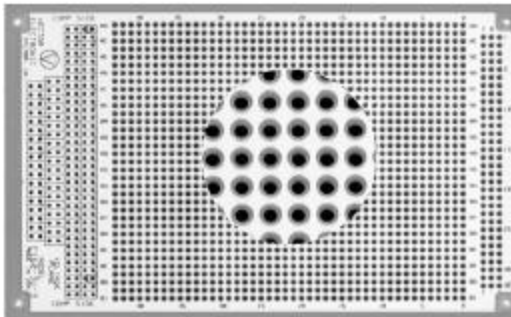
Pad-Per-Hole
6.30"/.062"
3.94"
35
FR4 Epoxy Glass
T44, T46, T49, T68
R32
CCK160-3U
RE96MWR
(Available Separately)
.042"

- 0.100" grid
- Voltage and ground buses around board perimeter, both sides
- Isolated solder pad around each hole, both sides
- Pad and bus surfaces solder-coated for user convenience
- For solder, Wire-Wrap or mixed wiring methods
- Layout paper and instructions included
- Row and column legends provided
- Plated-thru holes

E160-3U-2**3Ux160mm**

Pad-Per-Hole

- Power & GND planes both sides

**E160-3U-3**

Circuit Pattern:

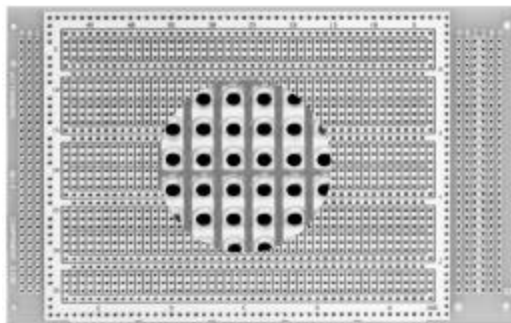
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Rec. Card Cage:
96-Pin Din Connector:

Hole Diameter:

3Ux160mm

Voltage Ground Plane
Both sides
6.30"/.062"
3.94"
45
FR4 Epoxy Glass
T44, T46, T49, T68
R50, R51, R52, R53
CCK160-3U
RE96MWR
(Available Separately)
.055"

- 0.100" grid
- Overall voltage and ground planes on opposite board sides provide excellent shielding and power distribution
- Plane surfaces solder coated
- To simulate plated-thru holes committed to voltage or ground planes, use Vector T123 eyelets, available separately (for use without pins)
- Layout paper and instructions included
- Row and column legends provided

**4614**

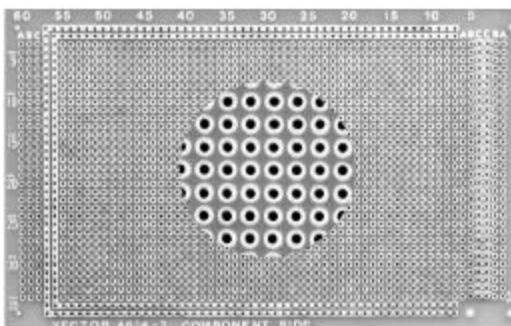
Circuit Pattern:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Rec. Card Cage:
96-Pin Din Connector:

Hole Diameter:

3Ux160mm

3-Hole Solder Pad
6.30"/.062"
3.94"
20
FR4 Epoxy Glass
T44, T46, T49, T68
R32
CCK160-3U
RE96MWR
(Available Separately)
.042"

- 0.100" grid
- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Interleaved buses on both sides, back-to-back
- Pad and bus surfaces solder-coated for user convenience
- Layout paper and instructions included
- Row and column legends provided
- Plated-thru holes

**4614-3**

Circuit Pattern:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Rec. Card Cage:
96-Pin Din Connector:

Hole Diameter:

3Ux160mm

Pad-Per-Hole
6.30"/.062"
3.94"
30
FR4 Epoxy Glass
T44, T46, T49, T68
R32
CCK160-3U
RE96MWR
(Available Separately)
.042"

- 0.100" grid
- Voltage and ground buses around board perimeter, both sides
- Pad and bus surfaces solder-coated for user convenience
- For solder, Wire-Wrap or mixed wiring methods
- Layout paper and instructions included
- Row and column legends provided
- Plated-thru holes

Vectorbord